

Design Considerations for High Frequency Magnetic Materials

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FAIR-RITE PRODUCTS CORP

Agenda

- Market Motivation
- Measurement of high frequency power loss.
- Leveraging Existing Materials in Emerging Application
- New Material Development
- The advantages of ferrite materials in power supply designs
- Important parameters of ferrite materials and their impact on performance, such as:
 - Permeability
 - Performance factor
 - Power Loss characteristics
- Guidelines to selecting the appropriate ferrite material
 - Operating conditions
 - Environmental factors
- Optimizing core configuration based on design limitations
 - Effects of size and geometry
 - Effects of DC and air gaps

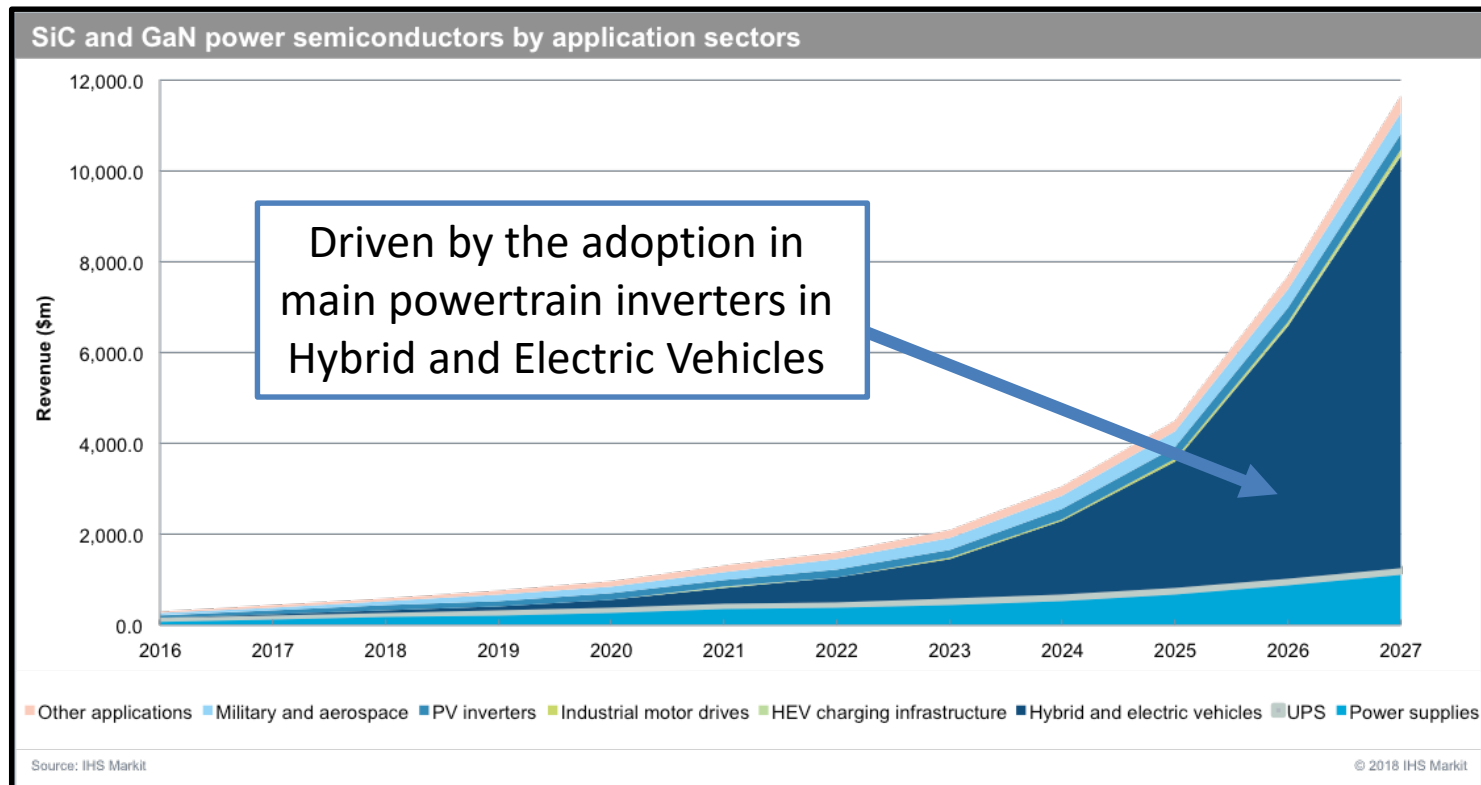
Market Motivation

- Miniaturization is a driving force in electronics design.
 - Magnetics are typically the largest component in power supplies.
 - In order to minimize power supply footprints, operating frequency has been increasing.
 - Power loss of magnetic components incorporated into these designs can cause issues with efficiency and heat management
- Increased efficiency
 - GaN has no reverse recovery charge which enables topologies such as the totem-pole PFC to improve efficiency



Markets for GaN and SiC

- GaN + SiC likely to reach ~\$10B by 2027¹
 - GaN is expected to achieve price parity with Si MOSFETs and IGBTs by 2020, leading to a CAGR = 21.5% from 2017 to 2025²



IHS Markit | Technology¹

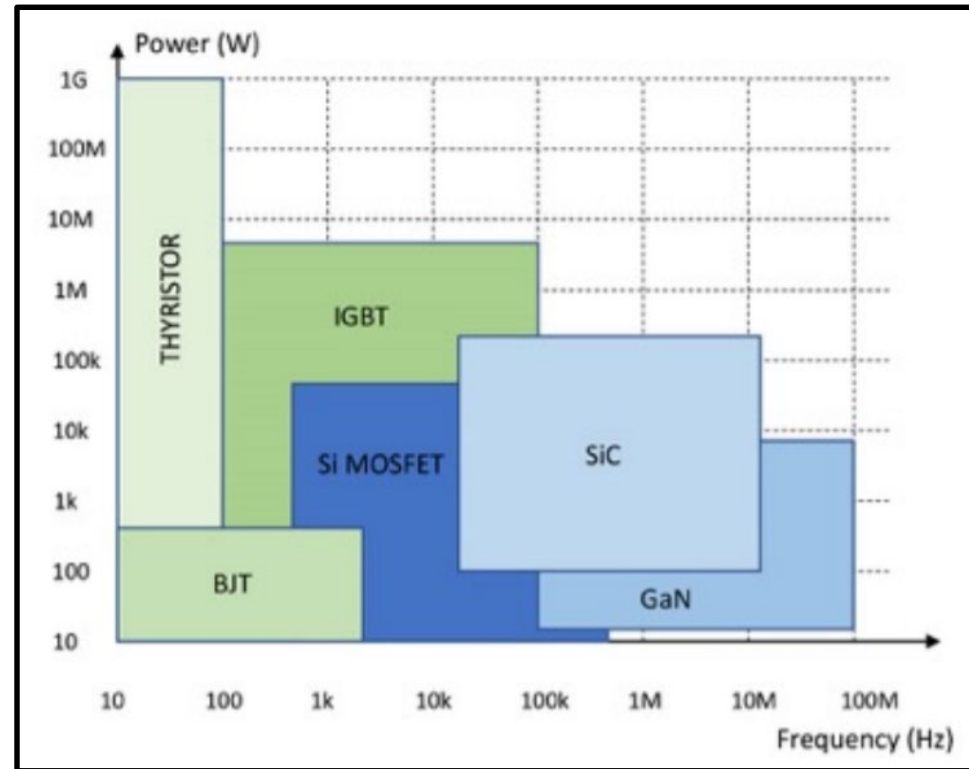
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Increasing Operating Frequencies

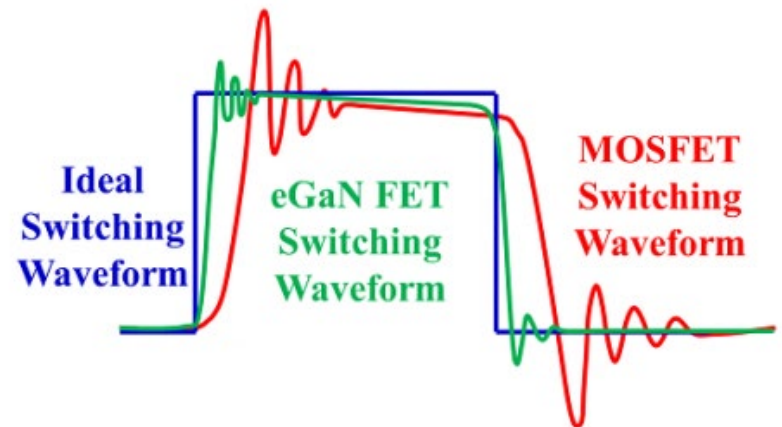
- **EPC:** “Cutting new ground for power transistors, these devices have switching transition speeds in the sub nano-second range, making them capable of hard switching applications above 10 MHz.”¹
- **GaN Systems:** “We have many customers using our devices from **hundreds of kHz, to 13.56MHz, and even some above 50MHz.**”²
- **Cree:** “Each gate drive circuit ... can comfortably switch the SiC MOSFETs at **up to 3MHz.**”³



Possible future scenario presented by UnitedSiC

Semiconductor Development

- “The rapid progress in GaN and SiC power semiconductors will lead to a further miniaturization of power electronic assemblies and subsystem...”
- **The drastically increased frequency requires improved ferrite materials with lowest losses.”**



Jungwirth,, H., Schmidhuber, M., Baumann, M., Schmeller, M.

“A new high frequency ferrite material for GaN applications”, PCIM Europe 2016.

Lidow, Alex. “How to GaN: eGaN® FETS in High Performance Class-D Audio Amplifiers.” *EE Web*. February 19, 2014.

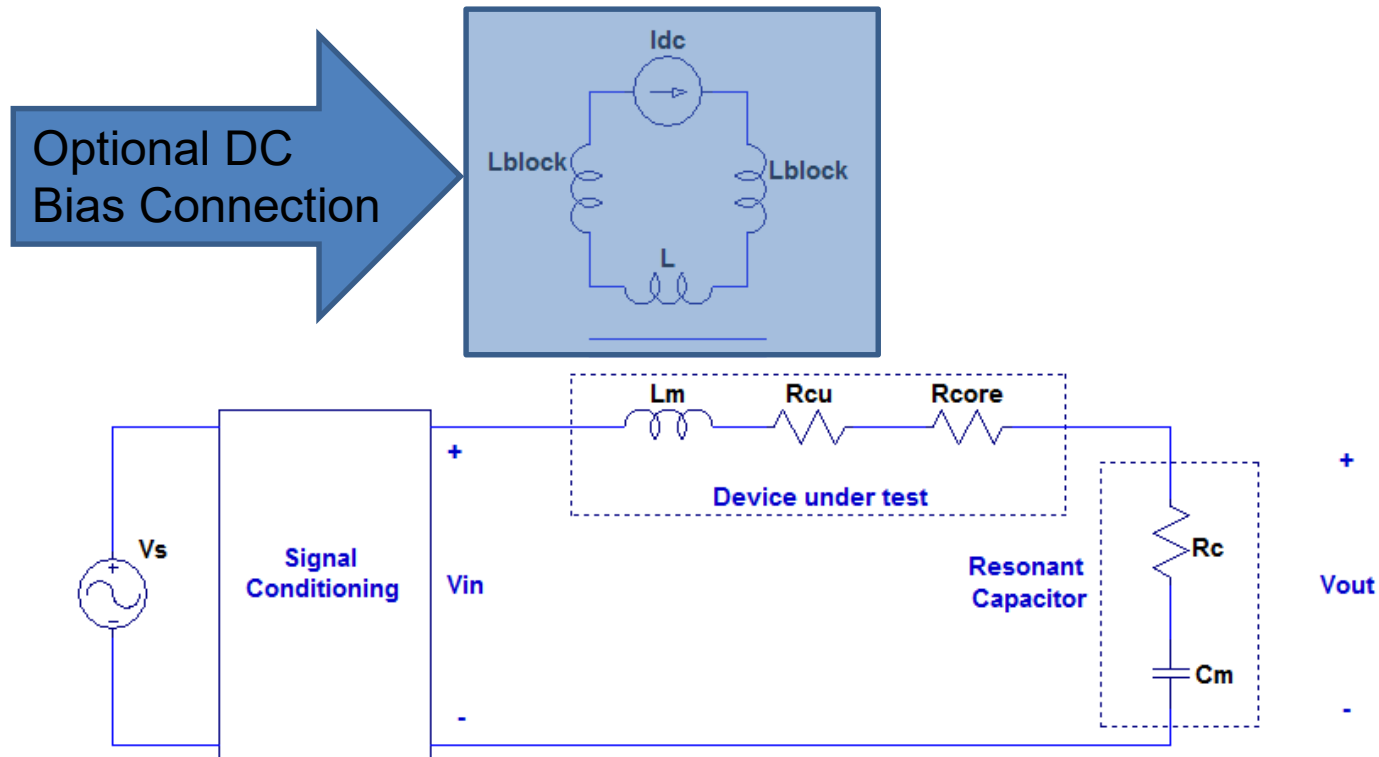
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Measurement Setup for Power Loss

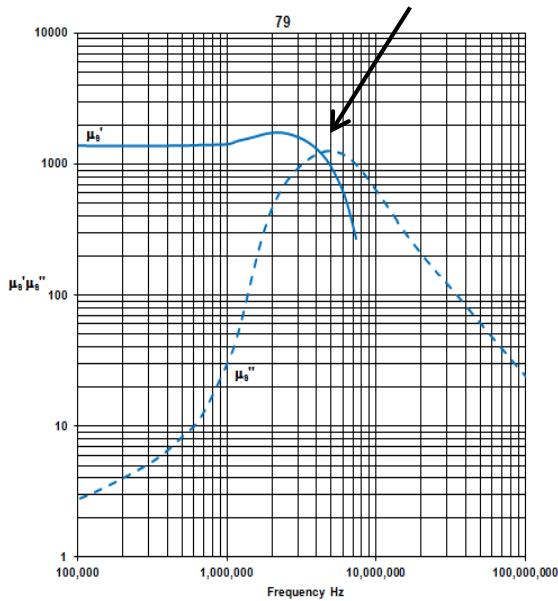
- Fair-Rite utilizes the “resonant Q” method developed by MIT to conduct measurements.
 - This system has been replicated at Fair-Rite with MIT’s assistance.
- This method removes the reliance on phase angle as part of the measurement.



(1) Han, Y; Cheung, G; Li, A; Sullivan, C.R.; Perreault, D.J.; “Evaluation of Magnetic Materials for Very High Frequency Power Applications” in Power Electronics, IEEE Transactions on , vol. 27, no.1, pp.425-435

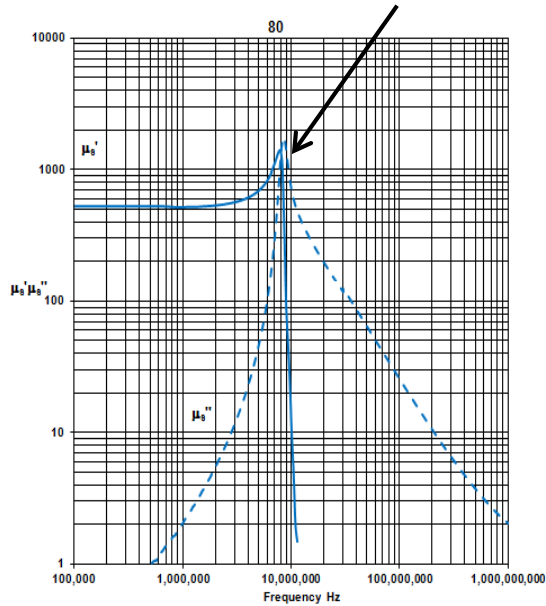
79 material

cut-off frequency 4MHz



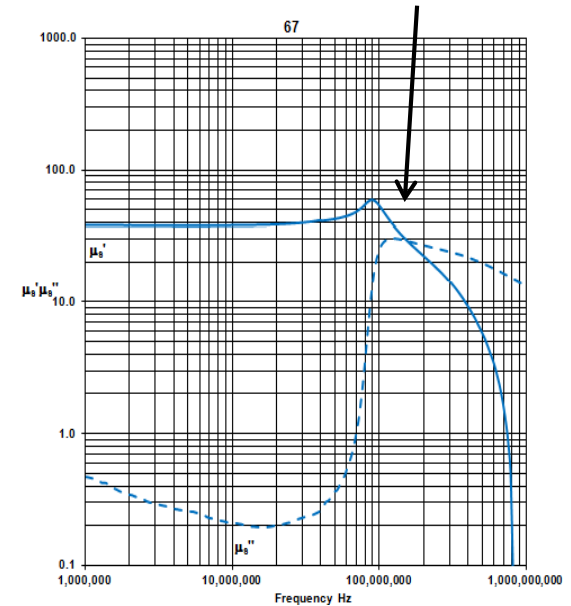
80 material

cut-off frequency 8MHz



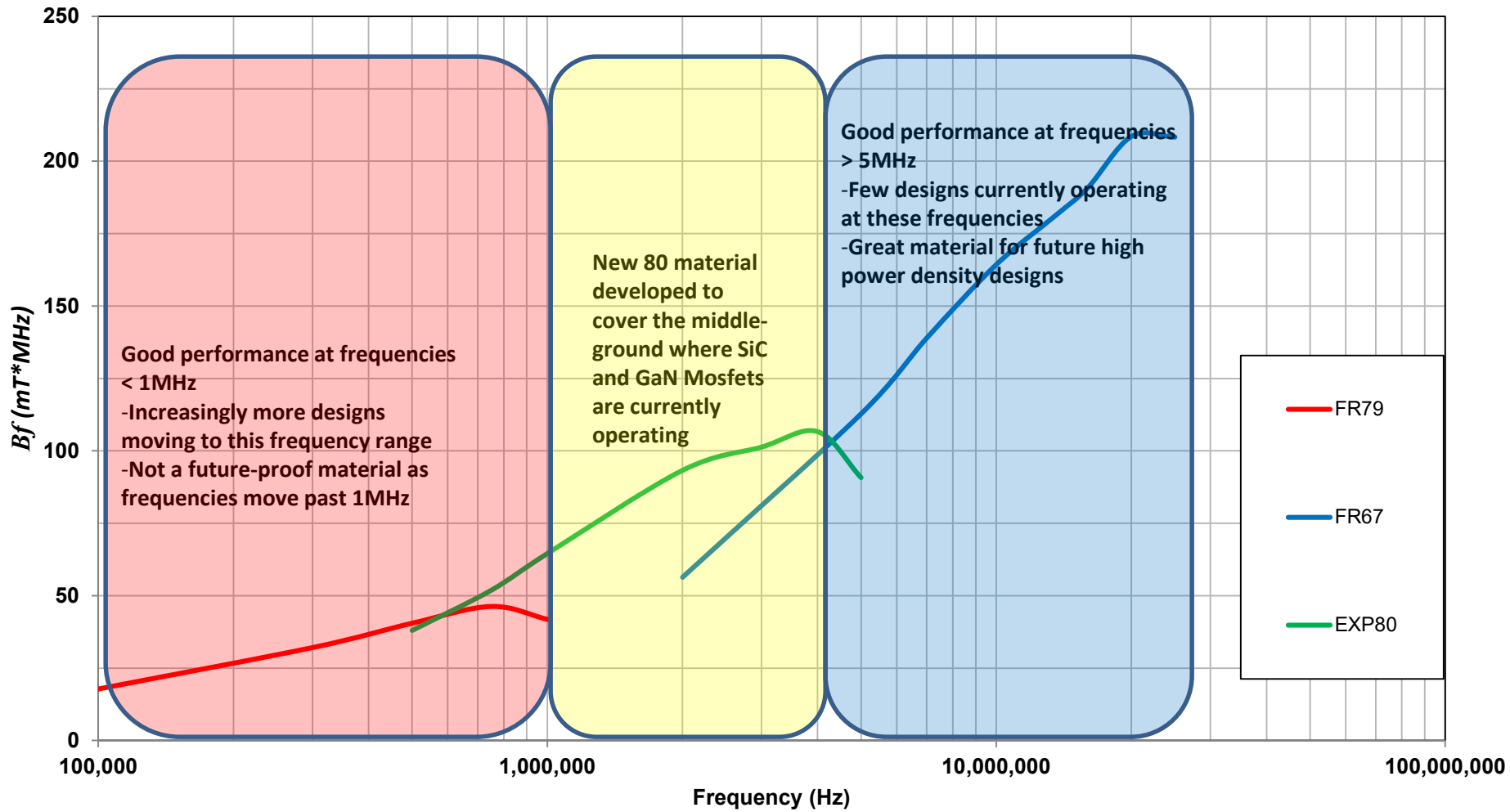
67 material

cut-off frequency 150MHz



- Loss factor is the principal loss parameter at low flux density (u''/u'^2)
- Typically lowest loss factor will have lowest core loss
- Higher cut-off frequency typically means lower core loss to higher frequencies

Performance Factor(500mW/cc) for Fair-Rite's Materials



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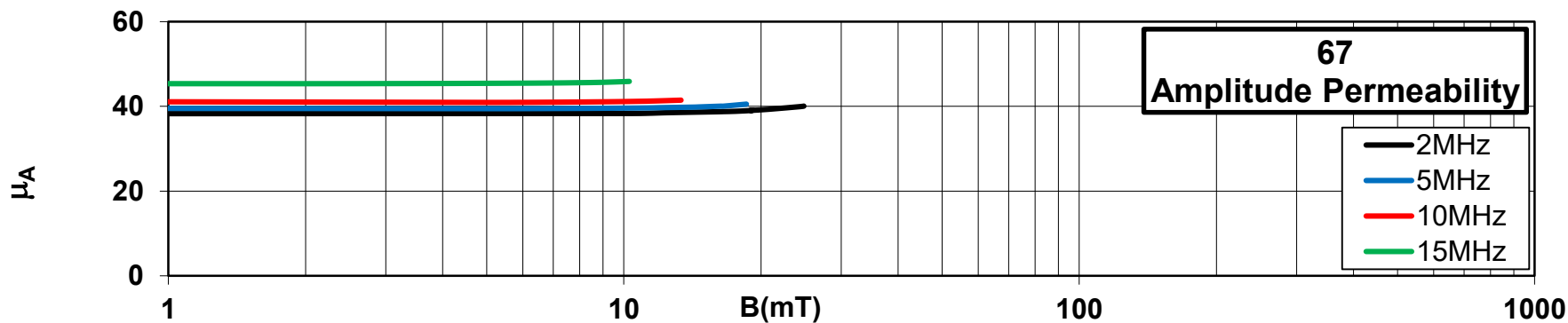
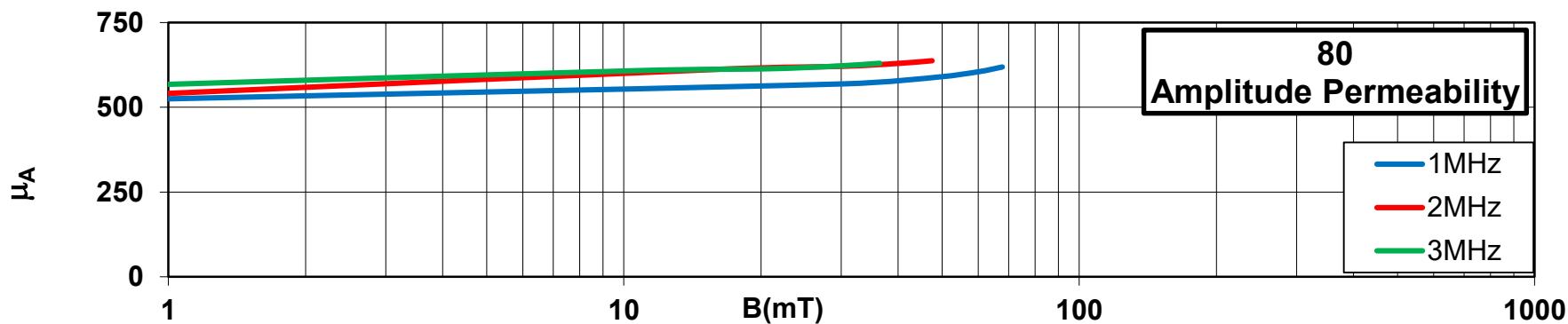
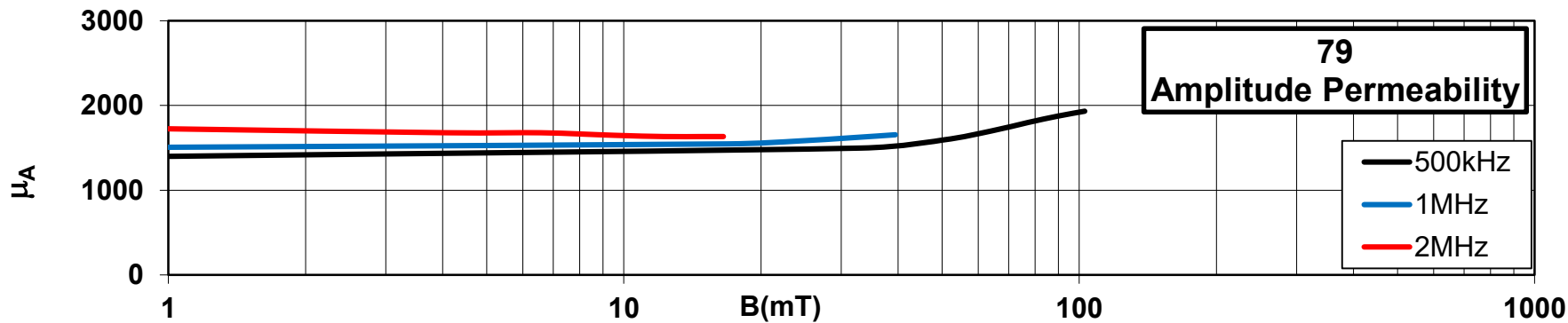
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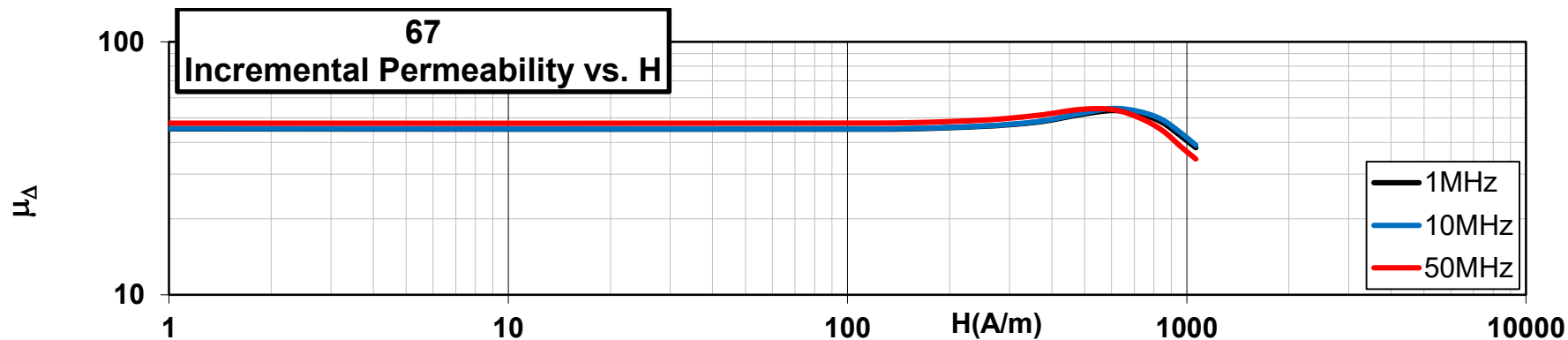
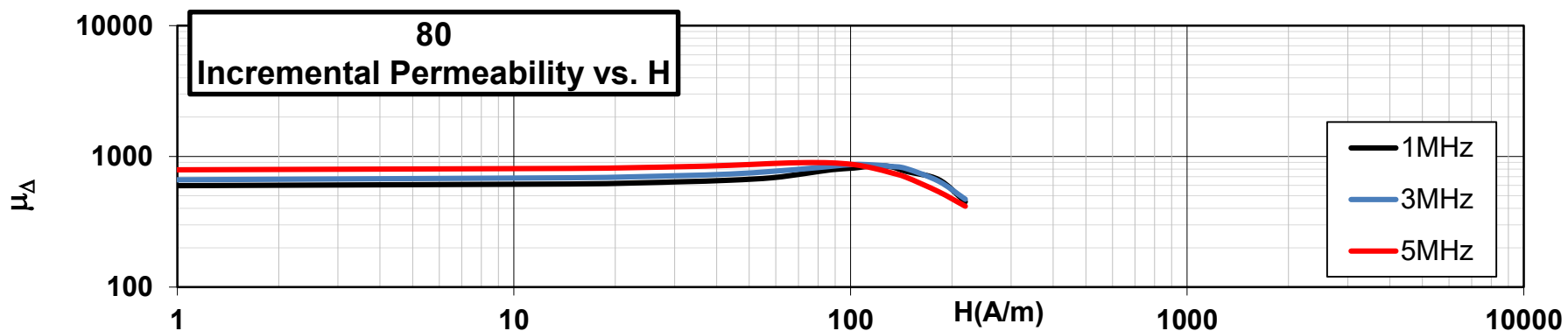
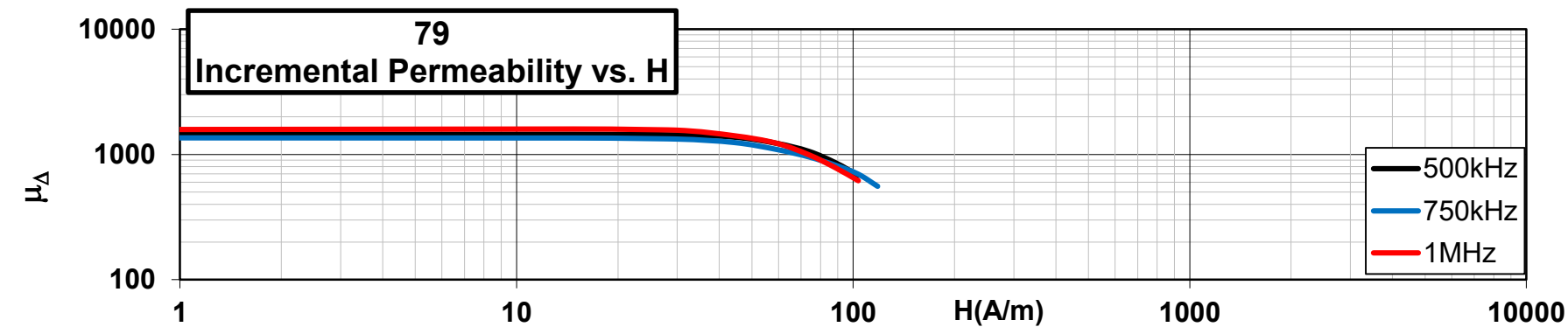
Considerations for selecting appropriate material and core configuration

- Permeability with:
 - Elevated flux densities
 - DC bias over frequency
- Power loss density
 - At operating frequency
 - Over temperature
- Optimal core size considering operating frequency.
- Geometry selection based on design requirements.
- Effects of DC bias on performance.
- Impacts of adding an air gap.

It looks like you're trying
to select a magnetic core.
Do you want my help?





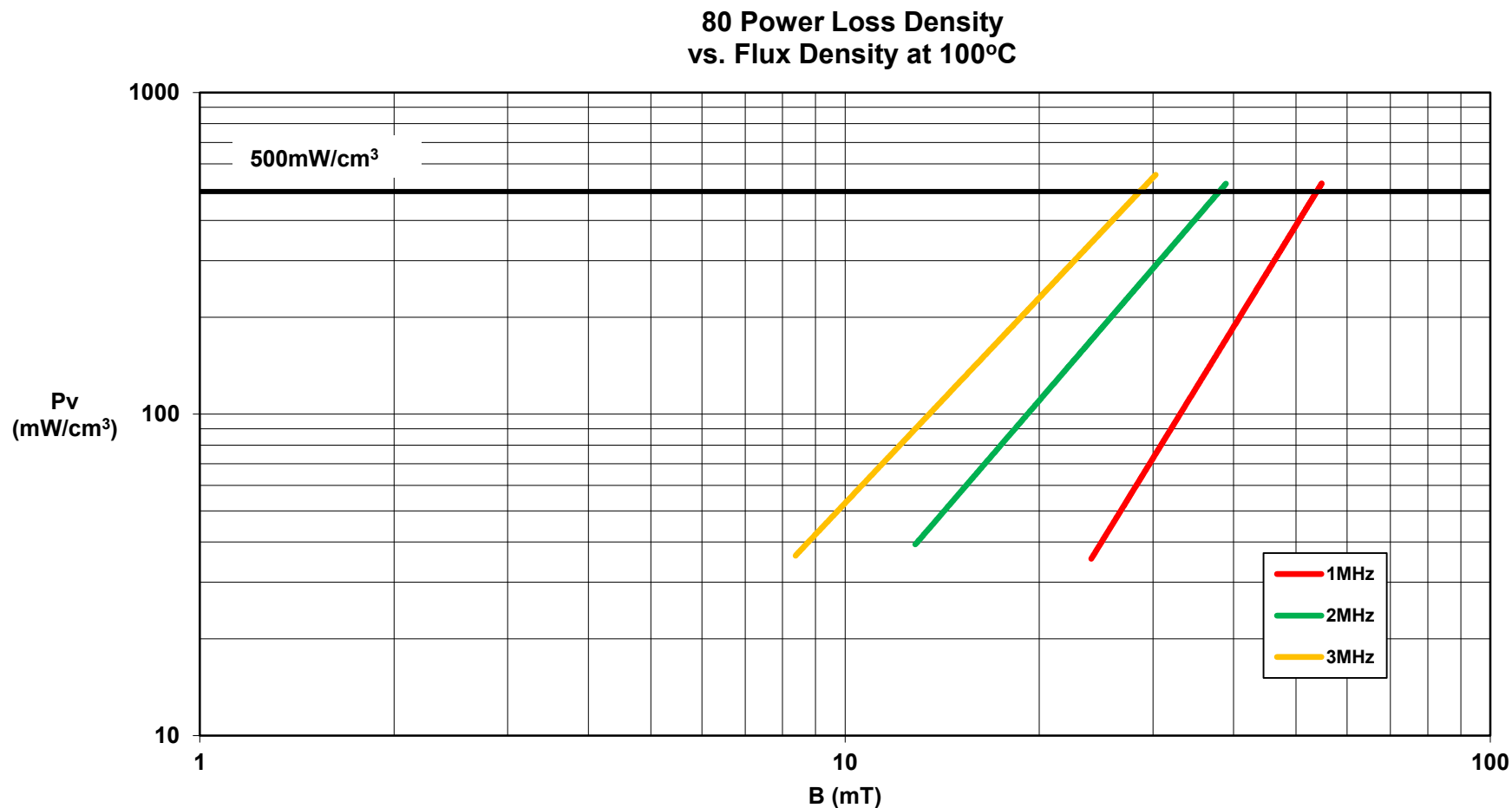


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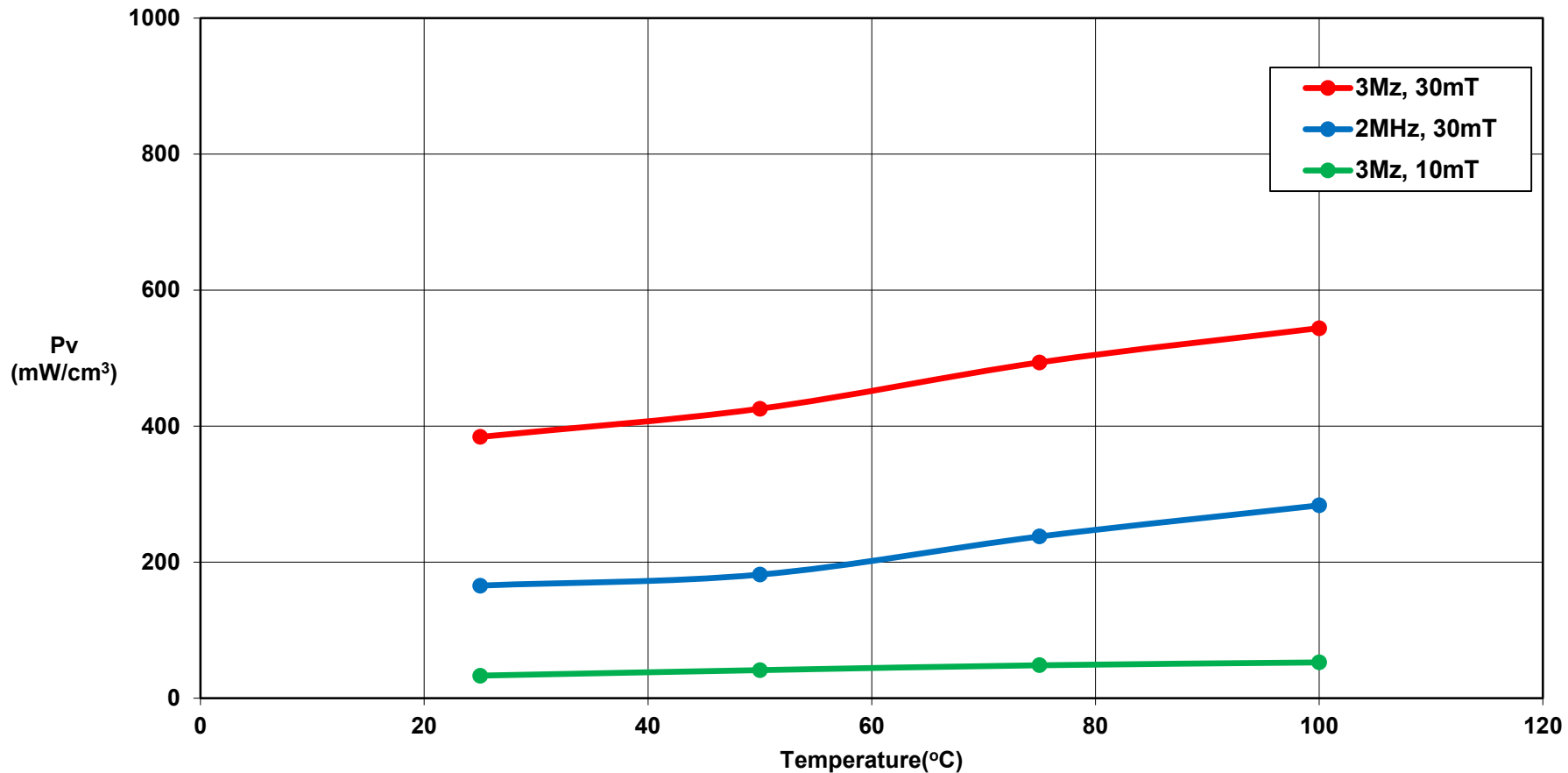
HF Power Loss Curves @ 100°C



Measured on a 22.1mm/13.7mm/6.35mm toroid at 100° C.

Power Loss vs. Temperature

80 Power Loss Density
vs. Temperature

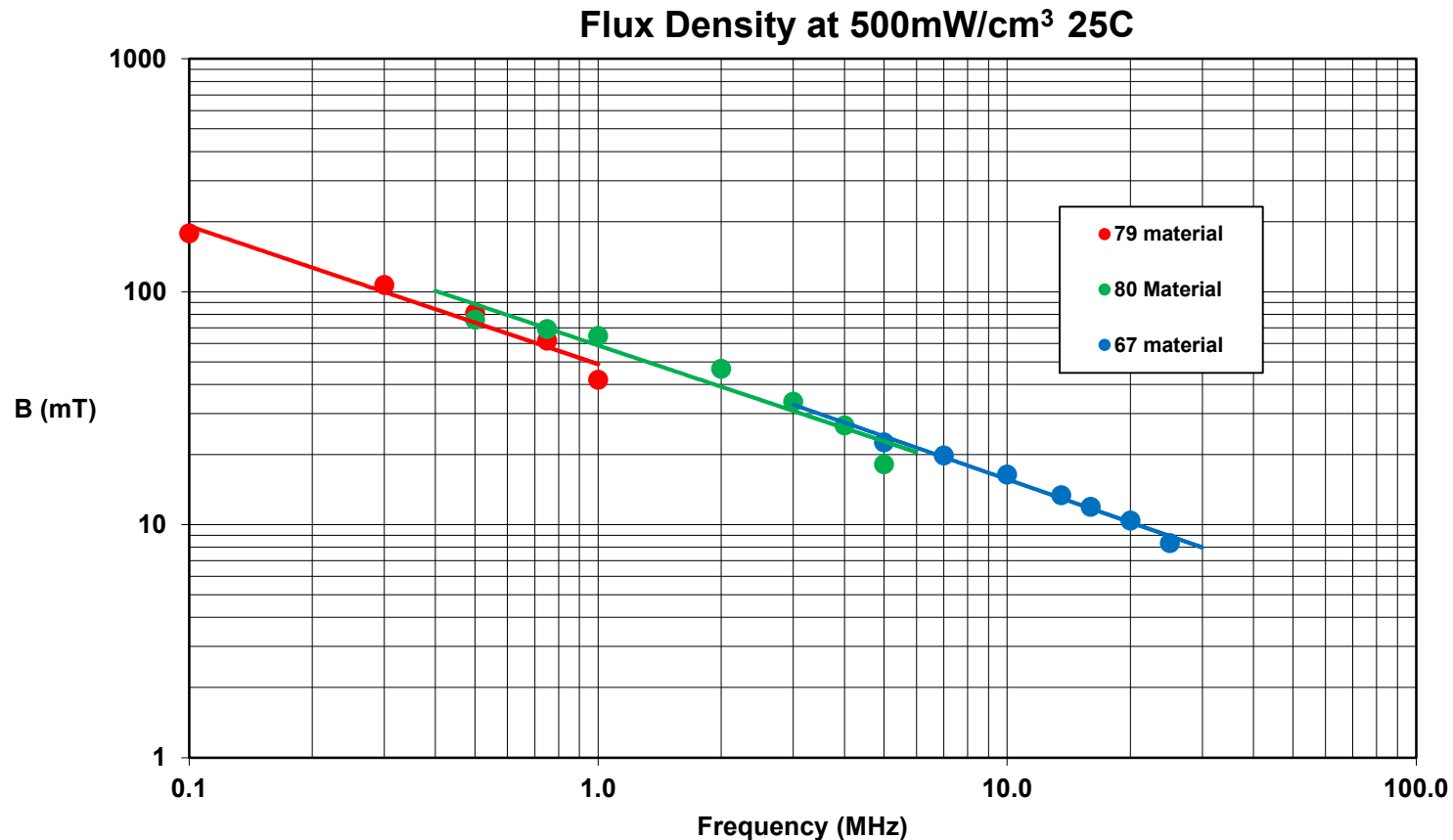


Measured on a 22.1mm/13.7mm/6.35mm toroid .

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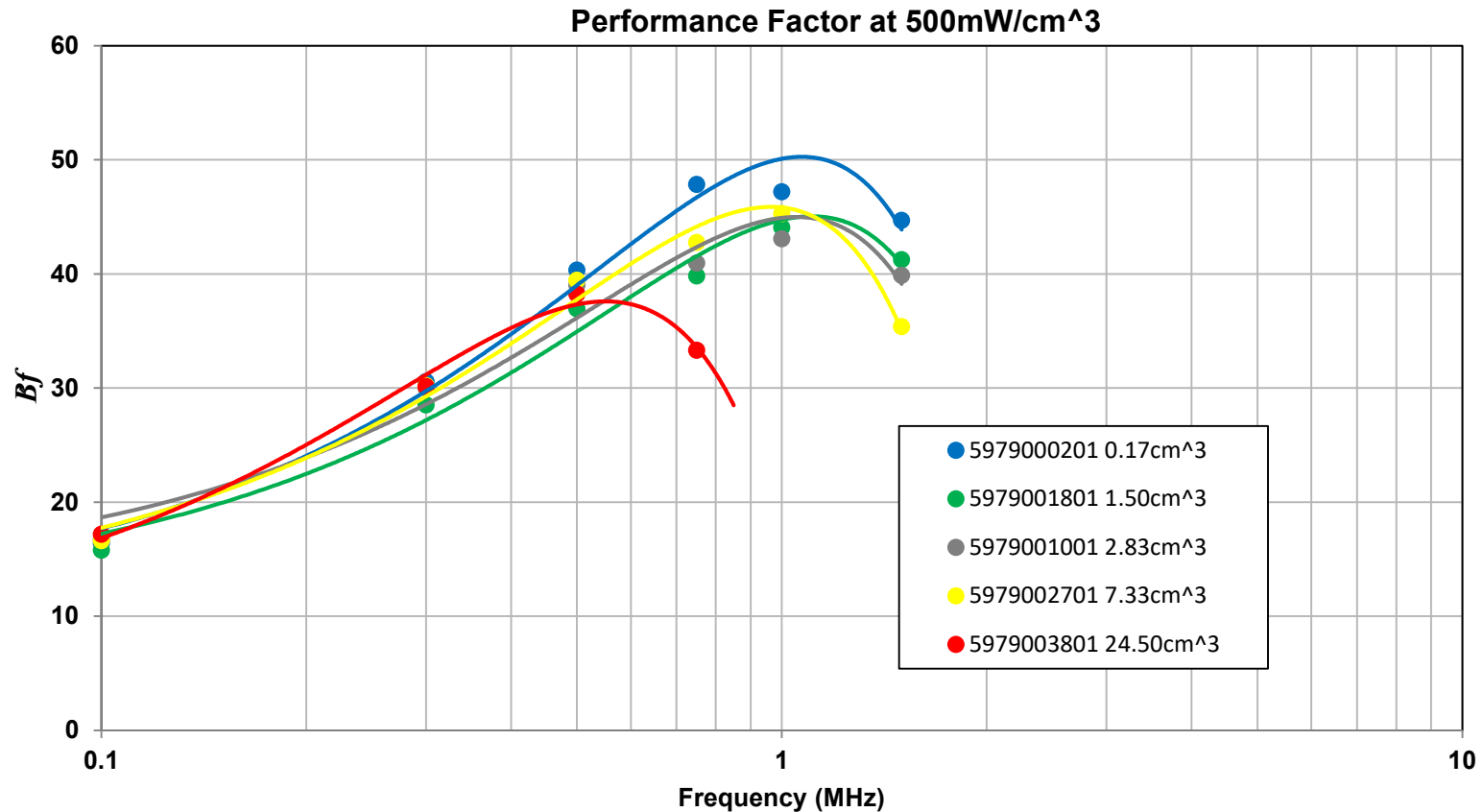
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Measured on a 12.7mm/7.9mm/6.35mm toroid at 25° C.

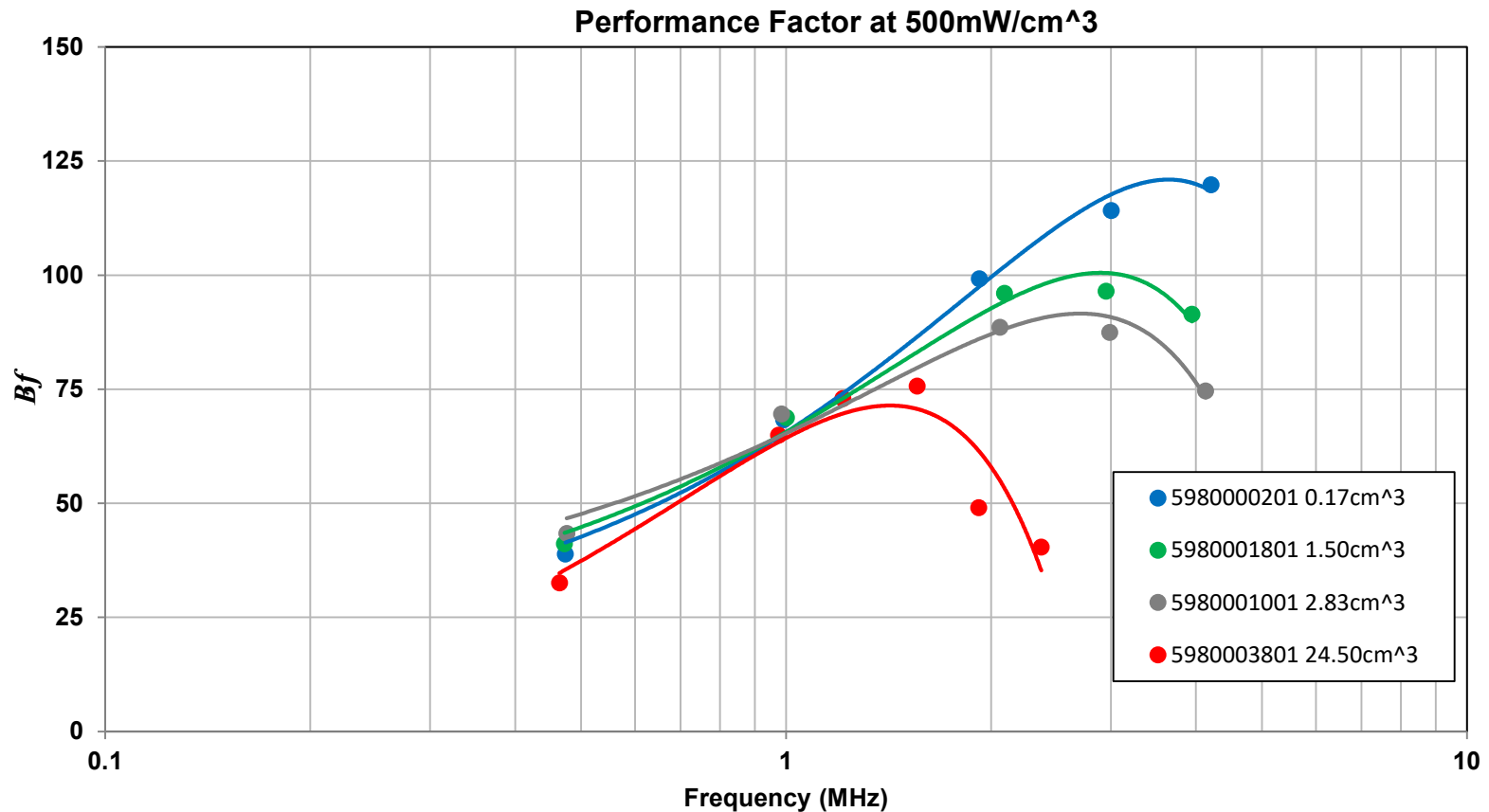
- For Power Conversion purposes operation should be limited to 500 mW/cc.
- For more conservative limiting of heat rise: 300 mW/cc is a better design constraint.
- At higher frequencies: operation is "loss limited" as opposed to flux density limited at low frequency.

Performance Factor Curves for different size 79 material toroids



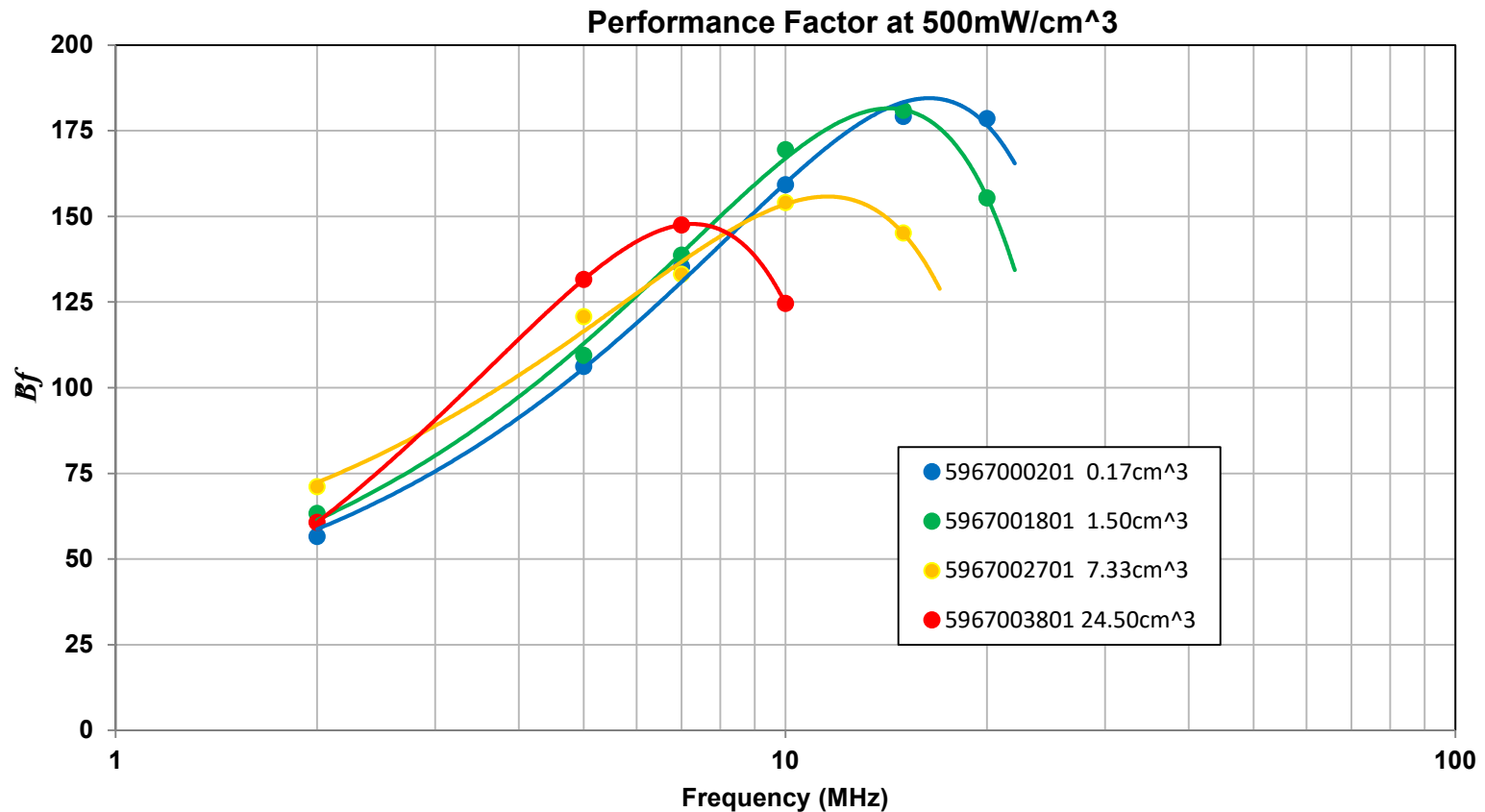
- Optimal operating frequency decreases as core size increases

Performance Factor Curves for different size 80 material toroids



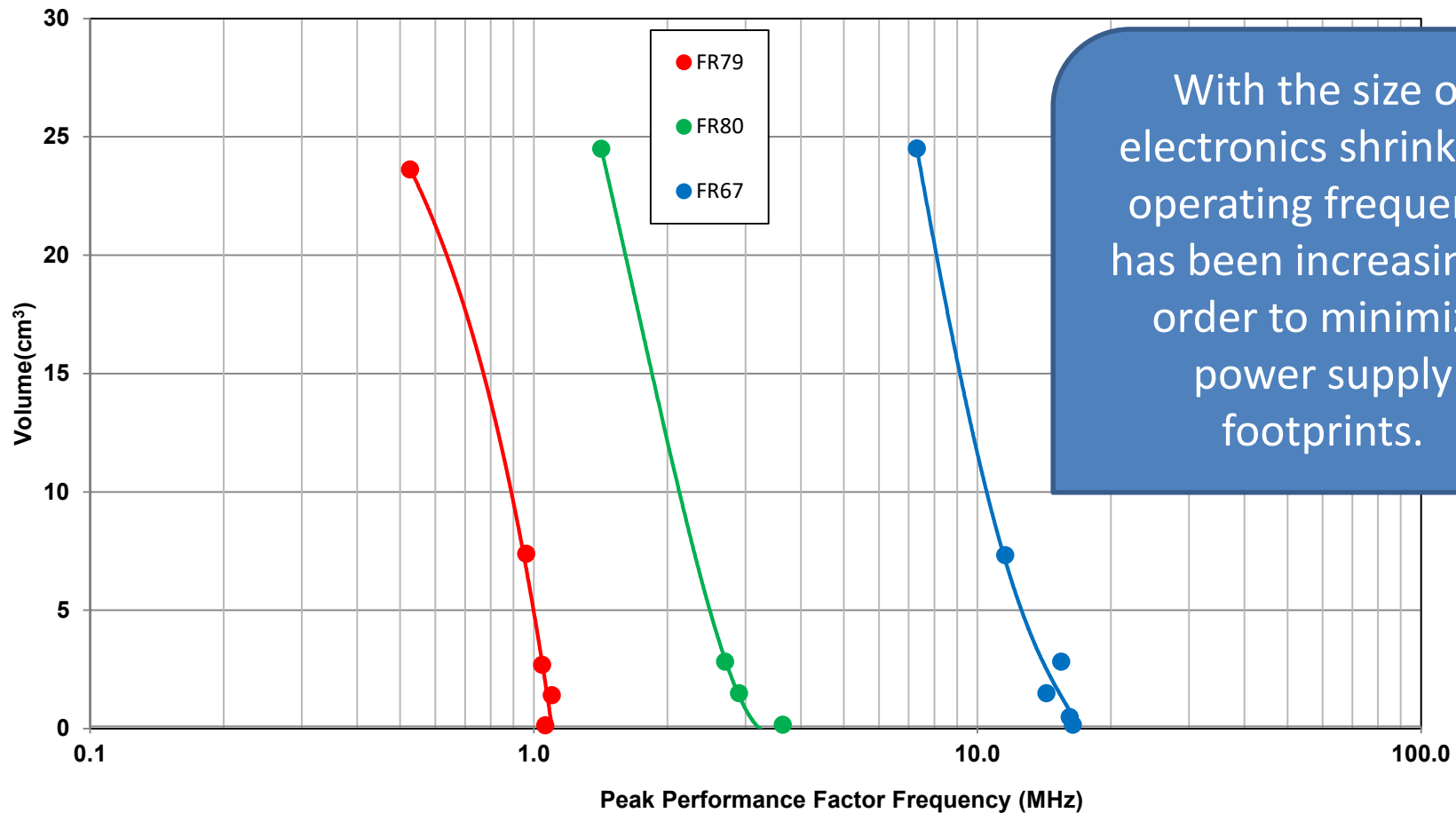
- Optimal operating frequency decreases as core size increases

Performance Factor Curves for different size 67 material toroids



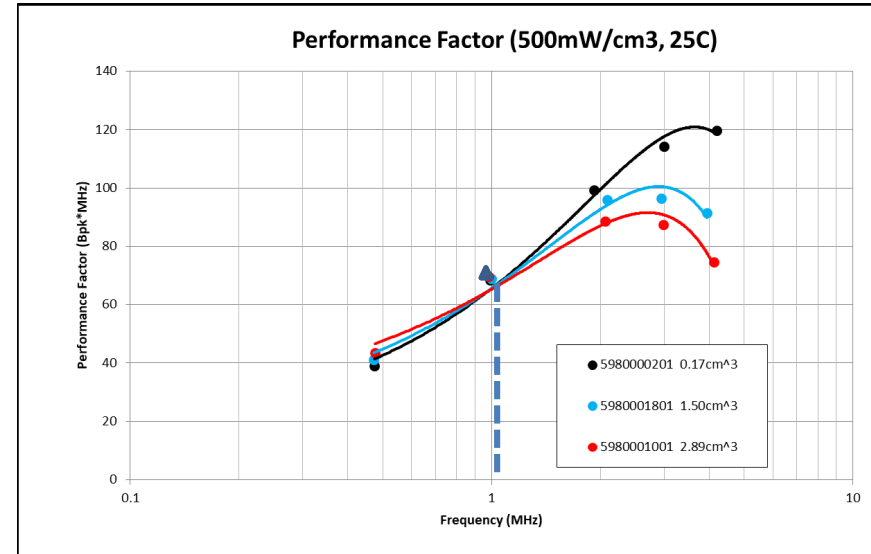
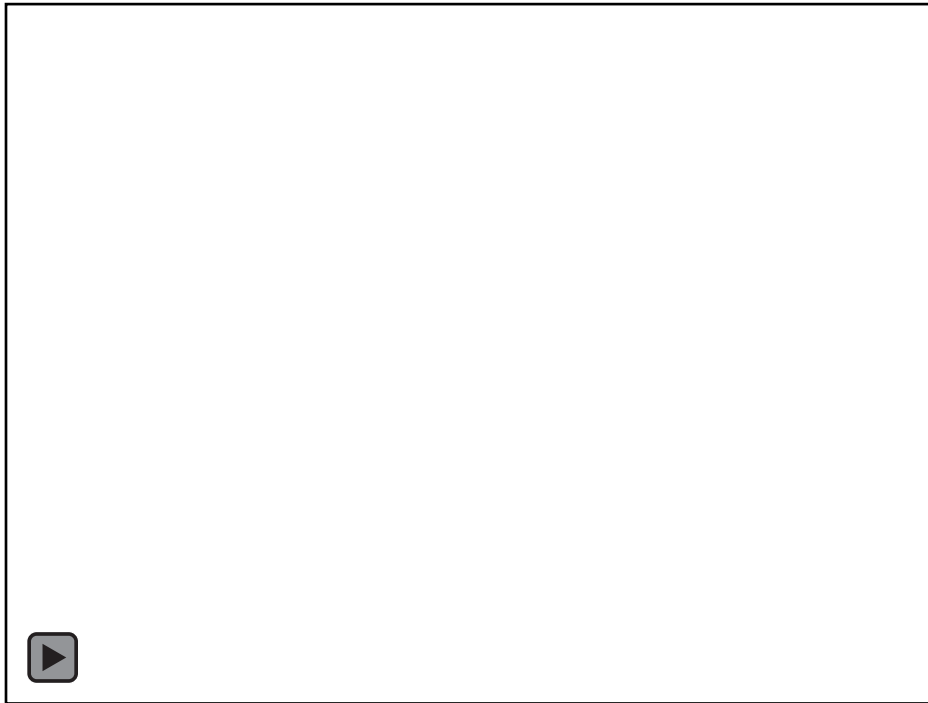
- Optimal operating frequency decreases as core size increases

Peak Performance Factor Frequency for Toroids



- Want to operate where performance factor is highest, but smaller cores cannot handle as high a power level.

Comparison #1



Max Temperature

46.3°C

53.3°C

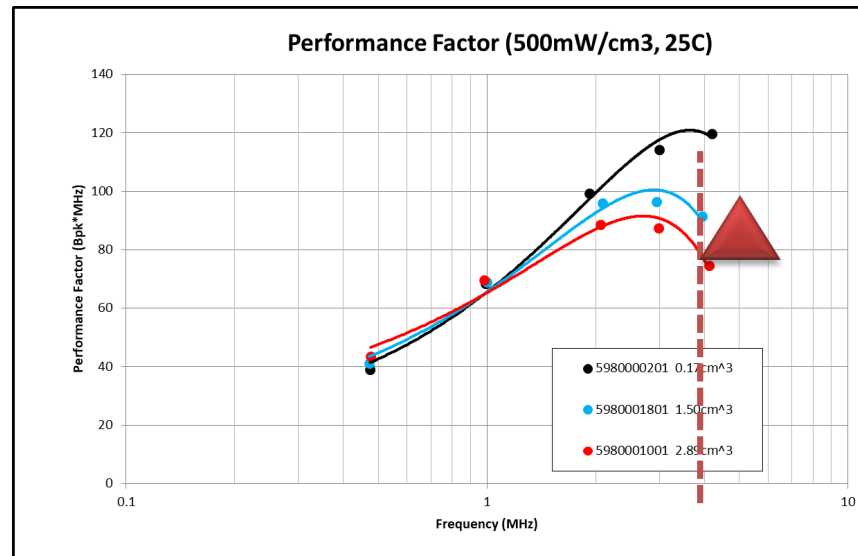
Maximum Temperature
Difference = 7°C.

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Comparison #2



Max Temperature

50.3°C

77.1°C

Maximum Temperature
Difference = 26.8°C.

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Considerations for Core Geometry Selection



- Power handling limited by temperature rise due to:
 - Copper losses of the windings
 - Power loss of the core
- Core size limited by available space on board
 - Low profile vs. large volume
- Magnetic shielding to limit EMI
- Cost and manufacturability

Desired Geometry Characteristics

Feature	Relation	Desired Ratio
inductance / length of wire	L_o/MTL	High
power-to-volume density	$A_e A_w / FP_{total}$	High
uniform cross section	A_{min}/A_e	High
magnetic shielding	Exposed Winding Area/Footprint	Low
heat dissipation	Exposed Winding Area/Footprint	High

Case study

- Geometries with largest physical dimension [A] in range of 20-30 mm and throughput power of 30-60 watts in traditional designs @ 100 kHz, < 200 mT*

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Comparison of the Different Geometries

<u>feature</u>	<u>T</u>	<u>std UU</u>	<u>std EE</u>	<u>P</u>	<u>EP</u>	<u>EFD</u>	<u>PQ</u>	<u>RM</u>	<u>ETD/ EER</u>	<u>pEE</u>	<u>pE I</u>	<u>pEER/ pEEQ</u>	<u>pERI/ pEQI</u>
inductance/wire length	2	1	1	3	4	1	2	2	1	4	5	3	4
power to volume density	5	5	5	2	2	3	3	3	4	3	2	3	2
off board height	3	1	2	3	1	4	2	2	2	4	5	3	5
round center post	5	1	1	5	5	1	5	5	5	1	1	5	5
uniform cross section	5	5	5	3	3	5	5	4	5	5	5	4	4
magnetic shielding	4	1	1	5	5	1	3	4	1	2	2	3	3
heat dissipation	4	5	5	1	1	4	4	2	5	4	3	4	3
core standardization	no	no	IEC	IEC	IEC	IEC	IEC	IEC	IEC	IEC	IEC	de facto	de facto
totals :	28	19	20	22	21	19	24	22	23	23	23	25	26
rating :	0.80	0.54	0.57	0.63	0.60	0.54	0.69	0.63	0.66	0.66	0.66	0.71	0.74



Rating: 1 to 5, where 1 is least and 5 is best.
 Note: Small 'p' indicated planar shape.



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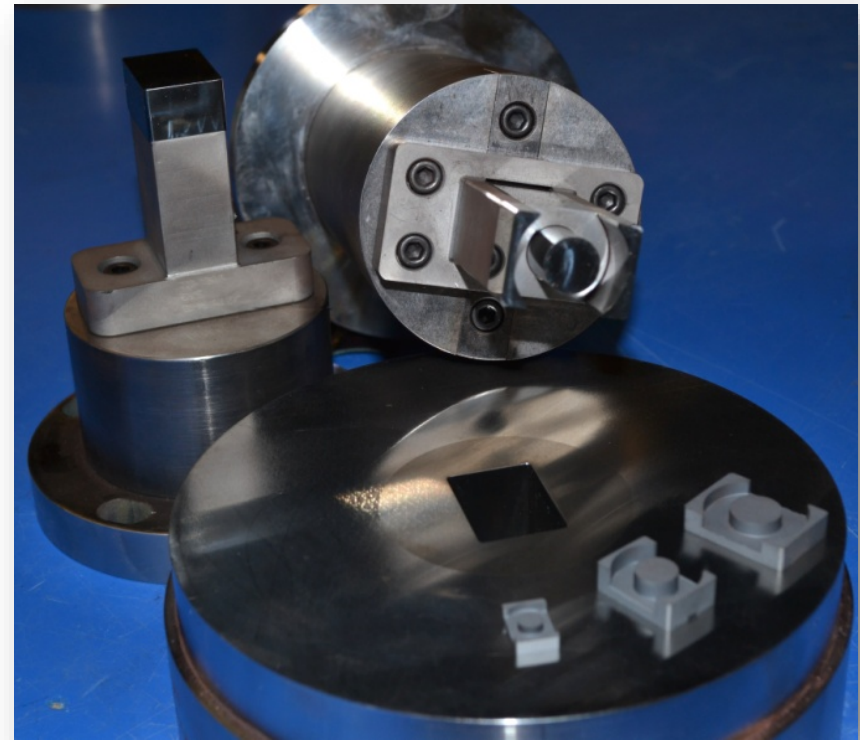
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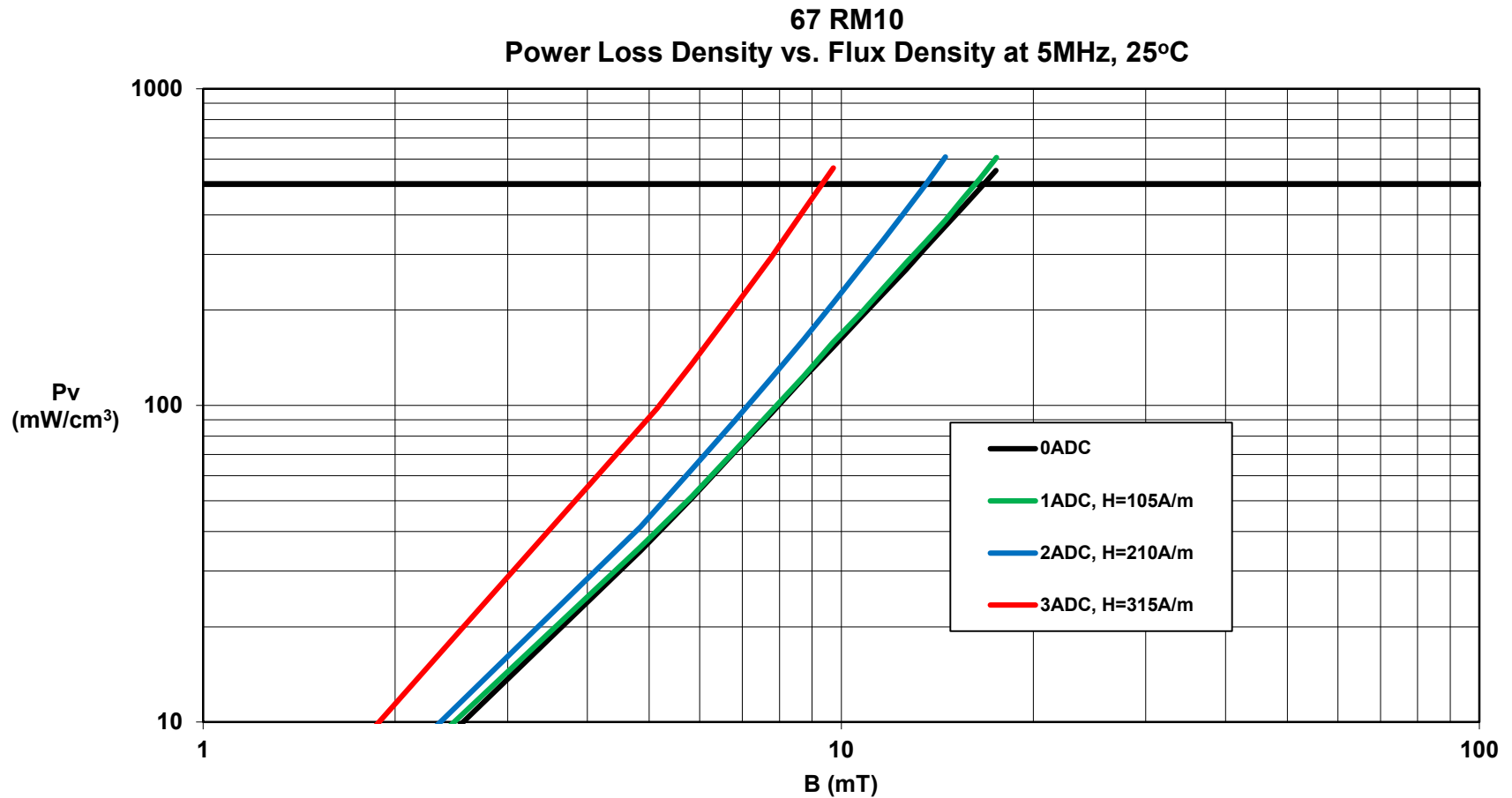
Geometry Conclusion

- Tradeoff of heat dissipation versus magnetic self shielding
- Center posts set back from the outer edge is most desirable for self shielding
- Maximum L_o/MTL is most desirable for lowest AC and DC copper losses
- Low A_w to A_e ratio pushes ratio of overall losses toward the ferrite instead of the winding
- Higher frequency operation requires less winding area because less inductance required

Toroids, Planar ER and EQ designs achieve best tradeoff for high frequency geometries

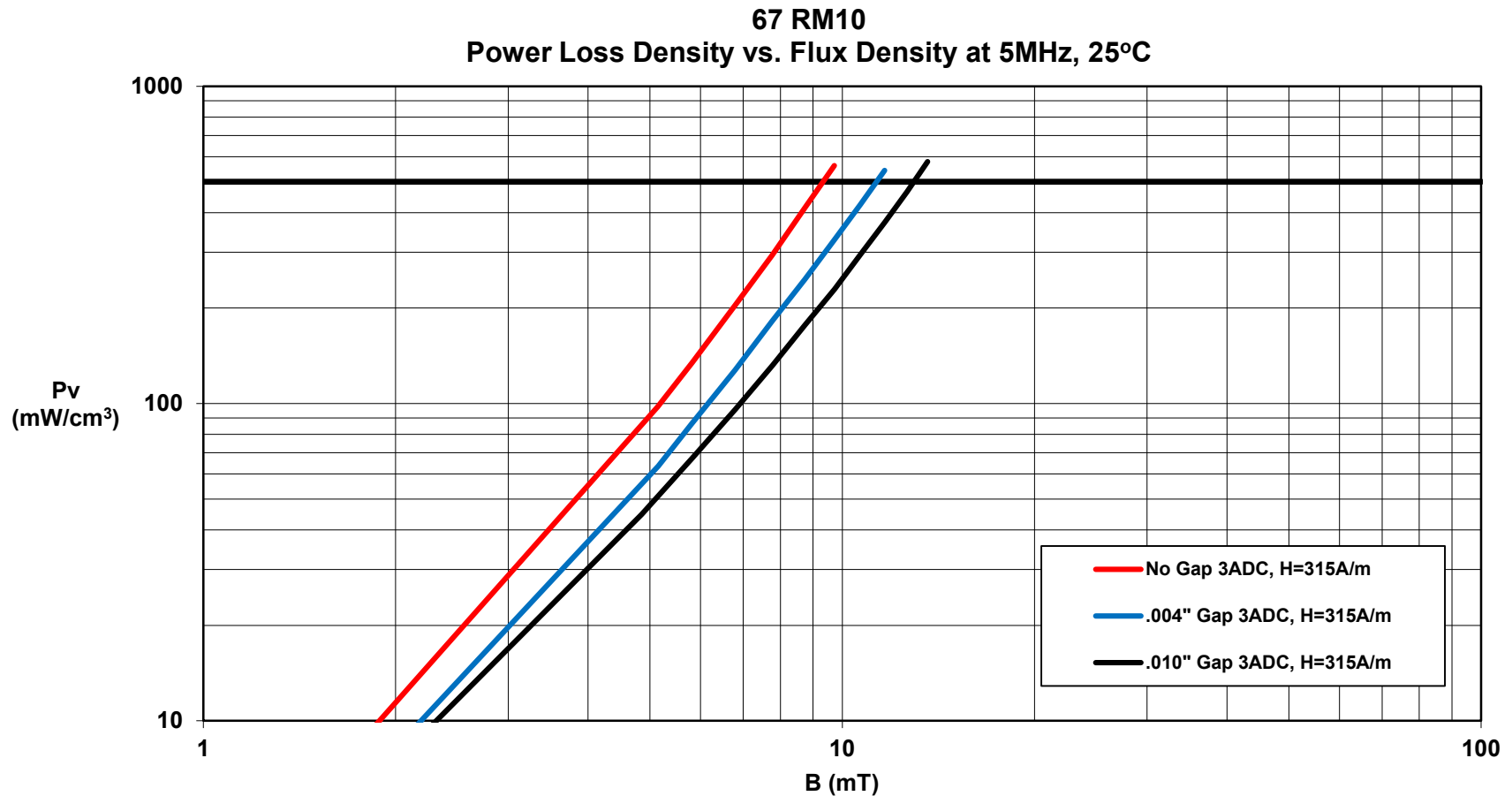


Effects of DC Bias



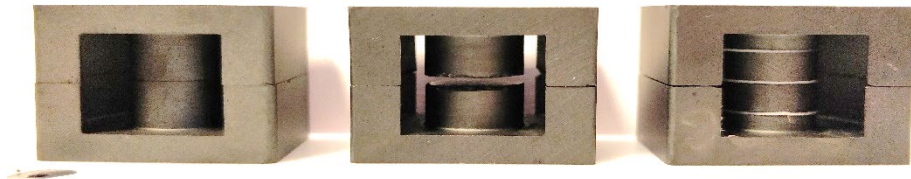
N=5

Effects of DC Bias with a Gap

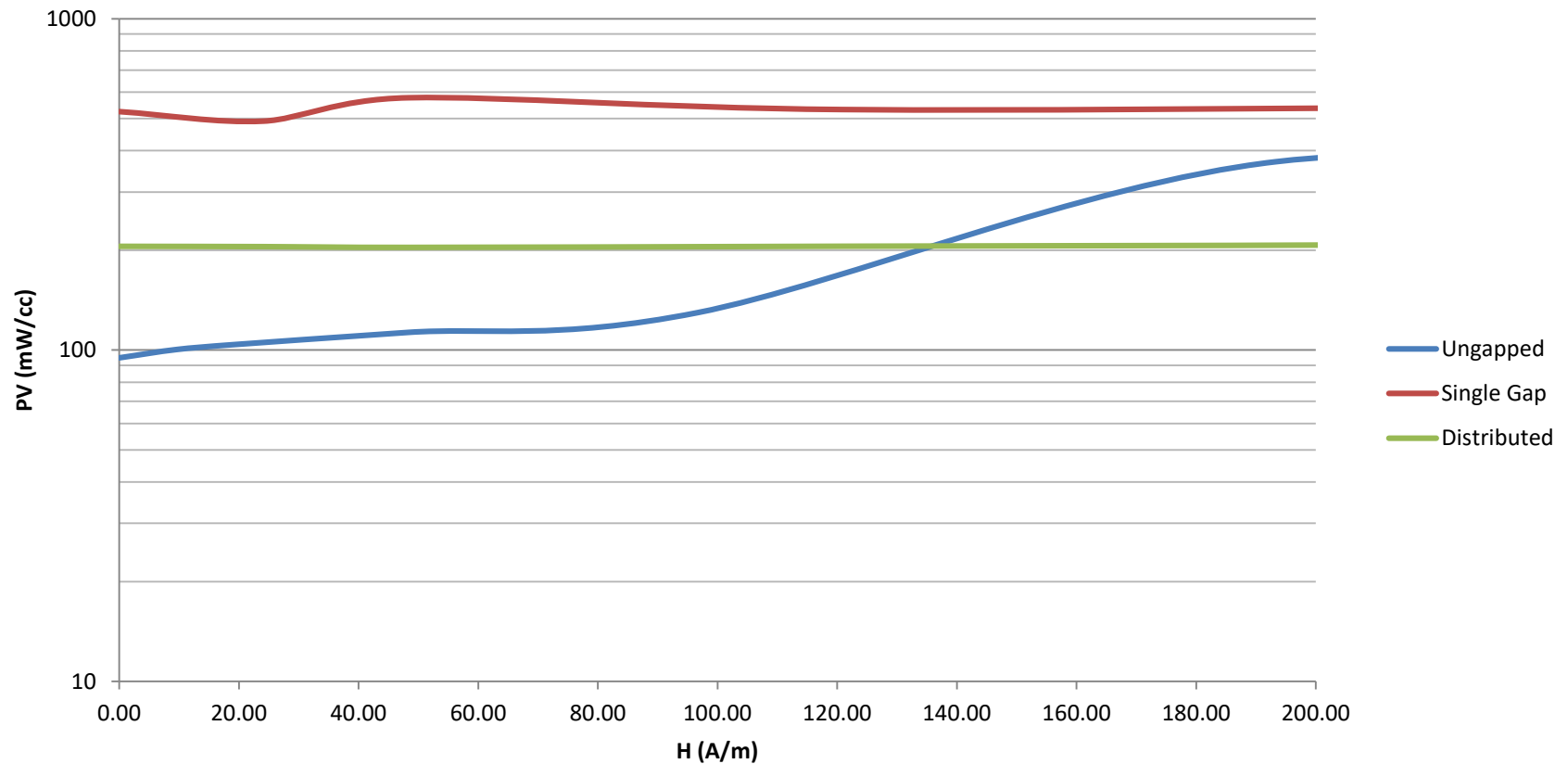


N=5

Effect of Bias



79 Material EQ25 1MHz 24mT

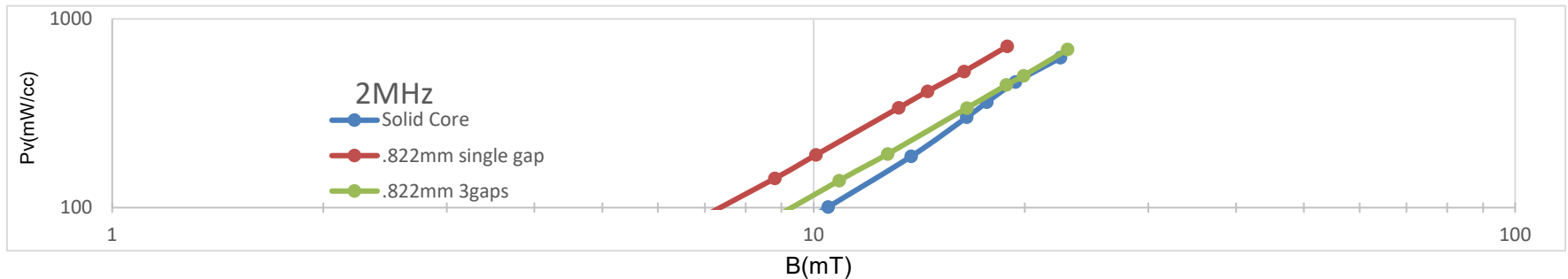
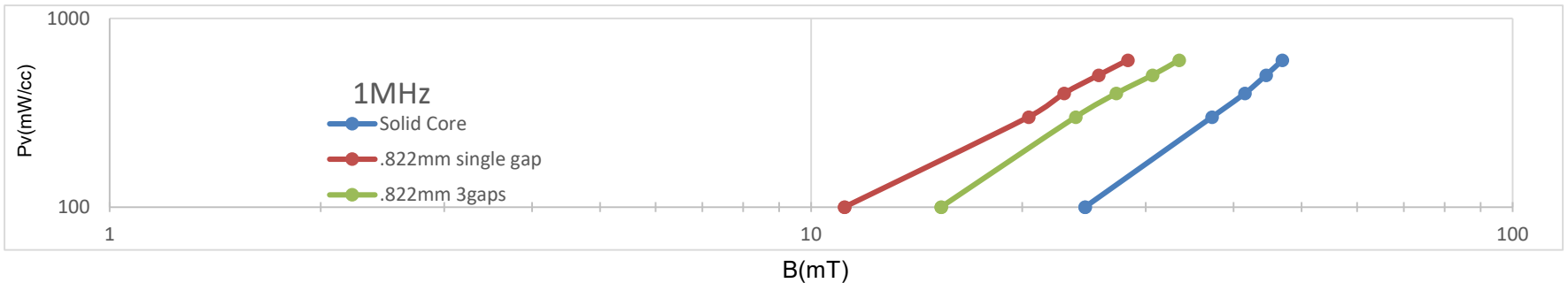
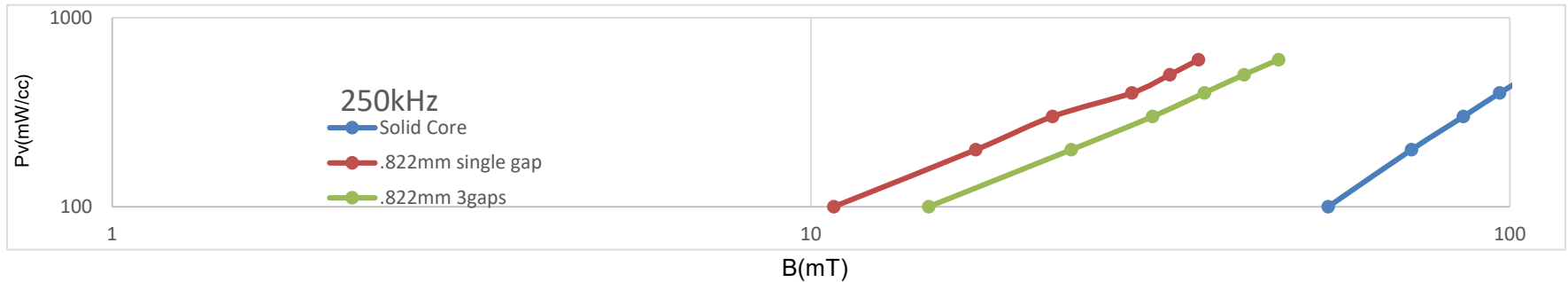


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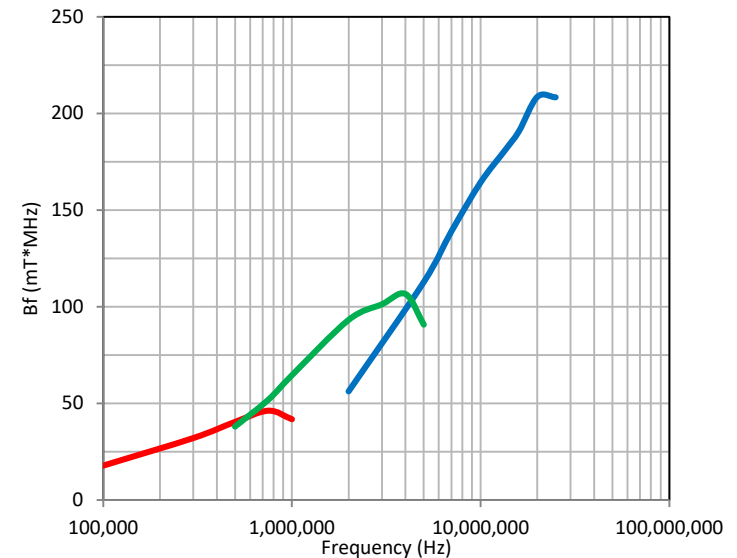
Power Loss 79 EQ25 Gapped vs Ungapped



As frequency increases, power loss due to gap becomes less significant

Summary

- Market moving toward higher frequency with smaller core sizes.
- Materials developed to cover the higher frequencies:
 - 79 material ($f < 1\text{MHz}$)
 - 80 material ($1\text{-}5\text{MHz}$), newly developed
 - 67 material ($f > 5\text{MHz}$), optimized
- 79, 80, and 67 offer:
 - Stable permeability with increased flux densities and DC currents over frequency.
 - Low power loss density at higher frequencies covering a range from 500kHz to over 10MHz .
 - Stable power loss densities over temperature.
- Fair-Rite currently offers toroids and EQ cores and continues to add new parts.
- Custom parts and evaluation kits available upon request.



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